



Volume 3

May 24, 2014

Welcome to Solutions Newsletter. This periodic newsletter provides information on our latest happenings and product updates.

Many thanks to our loyal customers for their continued interest in our products.

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SEMICON West 2014 July 8-10 Moscone Center, San Francisco

[IMAPS - 47th International Symposium on Microelectronics](#)

October 13- 16, 2014

Solutions Newsletter

For Dispense and Assembly

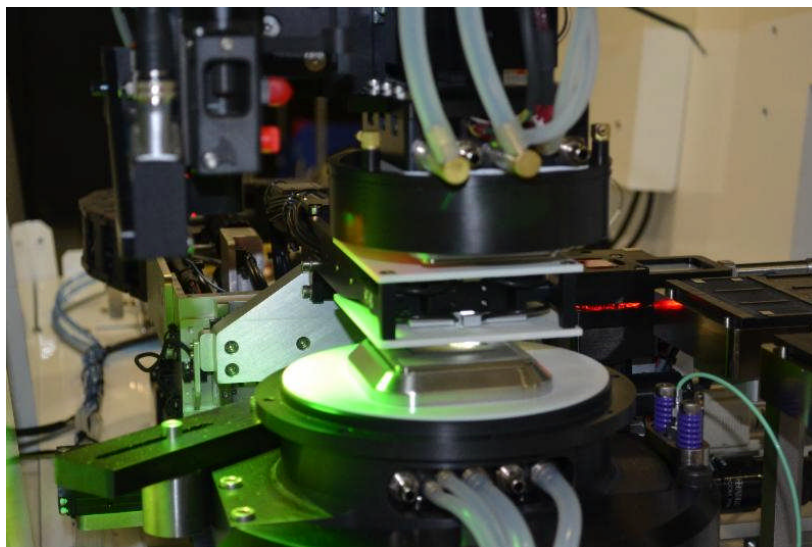
2.5D/3D Thermo Compression Bonder

MRSI Systems Announces 2.5D/3D Thermo Compression Bonder

MRSI Systems has been in development of an automated system and processes for thermo compression bonding that enables new methods of assembling semiconductor devices utilizing advanced electronics packaging technologies (including 2.5D/3D). The tool provides optimal tool design and process requirements for achieving successful (defect free) bonding. The development includes prototype tooling and processes for fluxless thermo compression bonding of flip chip die, as well as capillary underfill dispensing.

MRSI Systems is a leading supplier of high-performance, high-accuracy die bonding and dispensing systems to the microelectronics industry. MRSI is now applying its deep expertise in these areas to address the significant technological challenges of sub-3 micron thermo compression bonding of 2.5D and 3D devices and is partnering with a leading computer company in this effort.

"The increasing complexity and decreasing feature sizes of advanced semiconductor devices present significant challenges in the packaging process," said Mike Chalsen, President of MRSI Systems.



Come See Us at ECTC

The Electronic Components and Technology Conference (ECTC) is the premier international event that brings together the best in packaging, components and microelectronic systems science, technology and education in an environment of cooperation and technical exchange. ECTC is sponsored by the Components, Packaging and Manufacturing Technology (CPMT) Society of the IEEE. The 2014 ECTC will be held at the Walt Disney World Swan and Dolphin Resort, Lake Buena Vista, Florida, USA on May 27-30, 2014.

Come see us at ECTC 2014 in Orlando or you are always welcome at our Billerica, MA facility.



MRSI - M3
Assembly Work Cell



MRSI - M5
Assembly Work Cell



MRSI-705
Assembly Work Cell



MRSI-175Ag
Epoxy Dispenser



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